

**04-06 Aug, 2022. Seoul, Korea (Online & Offline)**

**Application Form**

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| --- | --- | --- |
| * **COUNTRY** | |  |
| * **Wiipa Member Name** | |  |
| **\* Inventors Name** | | **1.** |
| 2. |
| 3. |
| 4. |
| 5. |
| **Write the correct English name and affiliation name / Up to 5 People** |
| * **Name of**   **Agency (Contact)**  **or Contact Participant** | **Name** |  |
| **Tel** |  |
| **E-mail** |  |
| **Add** |  |

**. . 2022**

**Send to here**: E-mail / [Lee37895661@gmail.com](mailto:Lee37895661@gmail.com) / [7935111@naver.com](mailto:7935111@naver.com)

Date : \_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_

|  |  |
| --- | --- |
| **\*Name of Invention** |  |
| **\*Abstract Of Invention & Photo of Invention** |  |